

# APPROVAL SHEET

RFBPF 2012(0805) Series — RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER

2.4 GHz ISM Band Working Frequency

P/N: RFBPF2012090A2T

\*Contents in this sheet are subject to change without prior notice.

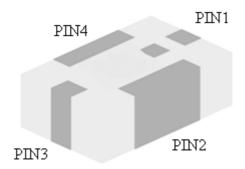
#### **FEATURES**

- 1. Miniature footprint: 2.0 X 1.2 X 0.9 mm<sup>3</sup>
- 2. Low Profile Thickness
- 3. Low Insertion loss
- 4. High Rejection Rate
- 5. High attenuation on 2<sup>nd</sup> harmonic suppressed
- 6. LTCC process

## **APPLICATIONS**

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, Wireless LAN 802.11b/g, HomeRF

## **CONSTRUCTION**



PIN	Connection			
1	Input port			
2	GND			
3	Output port			
4	GND			

Fig 1. Outline of 2.4GHz Band Pass Filter 2012 size

#### **DIMENSIONS**

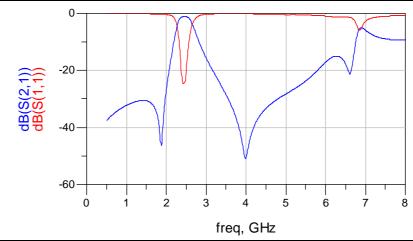
Figure	Symbol	Dimension (mm)
	L	2.00 ± 0.15
	W	1.25± 0.15
	Т	0.90 ± 0.10
A B	А	0.5 ± 0.15
	В	1.0 ± 0.15
	С	0.25 ± 0.15
	D	0.25 ± 0.15
	Е	0.45 ± 0.15
	F	0.35 ± 0.15



## **ELECTRICAL CHARACTERISTICS**

RFBPF2012090A2T	Specification		
Frequency range	2450 ± 50 MHz		
Insertion Loss	1.4 dB max		
VSWR	2.0 max		
Impedance	50 Ω		
	30dB @ 880~915MHz		
Attanuation ( min )	30dB @ 1710~1910 MHz		
Attenuation ( min.)	6dB @ 2110~2170MHz		
	20dB @ 4800~5000 MHz		
Operation Temperature Range -40°C ~ +85°C			

## **Typical Electrical Chart**



## **SOLDER LAND PATTERN**

Figure	Symbol	Dimension (mm)
7.1	L1	1.27 ± 0.10
L1	L2	0.51 ± 0.05
$\Phi$	L3	0.61 ± 0.05
S2 1 W1	L4	0.38 ± 0.05
$S3$ $\downarrow$ $L2$	L5	0.51 ± 0.05
$W_2$ $W_3$ $W_4$ $U_3$ $U_4$ $U_4$ $U_5$ $U_5$ $U_5$ $U_6$ $U_8$	W1	0.76 ± 0.10
	W2	1.02 ± 0.10
	W3	0.41 ± 0.05
	W4	0.76 ± 0.05
	S1	0.49 ± 0.05
Line width to be design to match $50\Omega$ characteristic impedance, depending on PCB material and thickness.	S2	0.25 ± 0.05
	S3	0.38 ± 0.05
Φ are the grounding through holes.	Φ	0.41 ± 0.10



## **RELIABILITY TEST**

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6	*Solder bath temperature : 235 ± 5°C	At least 95% of a surface of each terminal
JESD22-B102D	*Immersion time : $2 \pm 0.5$ sec	electrode must be covered by fresh solder.
	*Solder : Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150°C,  1 minute.  *Solder temperature : 270±5°C  *Immersion time : 10±1 sec  *Solder : Sn3Ag0.5Cu for lead-free  Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage.  Samples shall satisfy electrical specification after test.  Loss of metallization on the edges of each electrode shall not exceed 25%.
Drop Test JIS C 0044	*Height: 75 cm  *Test Surface: Rigid surface of concrete or steel.  *Times: 6 surfaces for each units; 2 times for each side.	No mechanical damage.  Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination  JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603)  *Test time : 10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec.  Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage.  Samples shall satisfy electrical specification after test.

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Temperature cycle JIS C 0025	<ol> <li>30±3 minutes at -40°C±3°C,</li> <li>10~15 minutes at room temperature,</li> <li>30±3 minutes at +85°C±3°C,</li> <li>10~15 minutes at room temperature,</li> <li>Total 100 continuous cycles</li> <li>Measurement to be made after keeping at room temperature for 24±2 hrs</li> </ol>	No mechanical damage.  Samples shall satisfy electrical specification after test.
Vibration JIS C 0040	*Frequency: 10Hz~55Hz~10Hz(1min)  *Total amplitude: 1.5mm  *Test times: 6hrs.(Two hrs each in three mutually perpendicular directions)	No mechanical damage.  Samples shall satisfy electrical specification after test.
High temperature JIS C 0021	*Temperature: 85°C±2°C  *Test duration: 1000+24/-0 hours  Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage.  Samples shall satisfy electrical specification after test.
Humidity (steady conditions) JIS C 0022	*Humidity: 90% to 95% R.H.  *Temperature: 40±2°C  *Time: 1000+24/-0 hrs.  Measurement to be made after keeping at room temperature for 24±2 hrs  % 500hrs measuring the first data then 1000hrs data	No mechanical damage.  Samples shall satisfy electrical specification after test.
Low temperature JIS C 0020	*Temperature : -40°C±2°C  *Test duration : 1000+24/-0 hours  Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage.  Samples shall satisfy electrical specification after test.

#### **SOLDERING CONDITION**

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

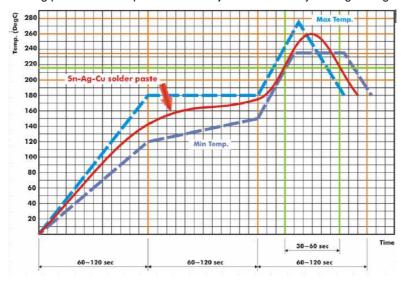


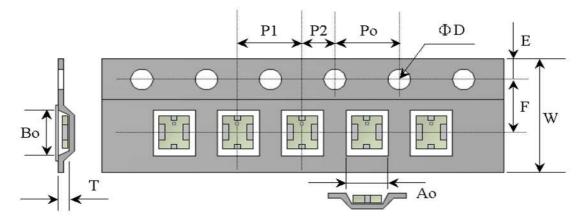
Fig 2. Infrared soldering profile

### **ORDERING CODE**

RF	BPF	201209	0	Α	2	Т
Walsin	Product	Dimension code	Unit of	Application	Specification	Packing
RF device	Code	Per 2 digits of Length,	dimension	A: 2.4GHZ ISM	Code from 0 ~ 9	T : Reeled
	BPF : Band	Width, Thickness:	0 : 0.1 mm	Band	dependent on	
	Pass Filter	e.g. :	1 : 1.0 mm		different electrical	
		201209 =				
		Length 20,				
		Width 12,				
		Thickness 09				

Minimum Ordering Quantity: 2000 pcs per reel.

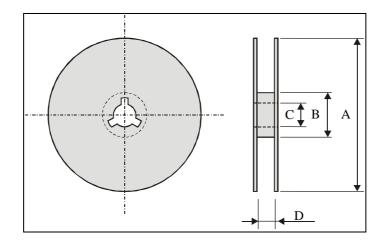
## **PACKAGING**



## Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	T	W
Dimension (mm)	1.45 ± 0.10	$2.25 \pm 0.10$	$1.55 \pm 0.10$	$1.10 \pm 0.10$	$8.00 \pm 0.30$
Index	Е	F	Po	P1	P2
Dimension (mm)	1.75± 0.10	$3.50 \pm 0.05$	4.00 ± 0.10	4.00 ± 0.10	2.00± 0.10

#### Reel dimensions



Index	Α	В	С
Dimension (mm)	Ф178	Ф60.0	Ф13.5

Taping Quantity:2000 pieces per 7" reel

#### **CAUTION OF HANDLING**

#### **Limitation of Applications**

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

## Storage condition

- Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
  - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.